

"Emerging Information Sharing and Design Technologies on Robotics and Mechatronics Systems for Intelligent Manufacturing "

The Theme: Today, robotics and precision stages have been intensively used in the intelligent manufacturing automation processes. The ultimate goal for intelligent manufacturing is to achieve the intelligent flow of material, information, energy and capital within the automation lines, by the backup of latest robotic technologies with blending of software and hardware, virtual and actual, human and machines. Eventually, the introduction of new concept of mechanism design, with fusion of low-cost sensor and novel way of information sharing and intelligent control, will enable great potential to improve the precision and dexterity of automation solutions for mass market. Hence, this special issue is targeted to gather the reports on latest developments on the new design, function, build-in intelligence, and applications on robotics and mechatronics systems.

The scope of this special section included, but not limited to

novel design and intelligent control for series, parallel or hybrid mechanism; new design and optimization for special actuators, joints and modules for slim and detextrious manipulating systems; design and intelligent control of soft robotics and haptics; multi-robotic system collaborative work; Integration between robotics systems and Internet of Things (IoT); VR/AR in the robotics systems; pattern recognition in robotic and mechatronic systems; e-automation; e-manufacturing.

Manuscript Preparation and Submission

Follow the guidelines in "Information for Authors" in the IEEE- IES website: <http://www.ieee-ies.org/pubs/transactions-on-industrial-informatics>. Please submit your manuscript in electronic form through Manuscript Central web site: <https://mc.manuscriptcentral.com/tii> . On the submitting page #1 in popup menu of manuscript type, select: SS on **Emerging Information Sharing and Design Technologies on Robotics and Mechatronics Systems for Intelligent Manufacturing**.

Submissions to this Special Section must represent original material that has been neither submitted to, nor published in, any other journal. Regular manuscript length is 8 pages, additional 4 pages may be allowed for a fee.

Note: The recommended papers for the section are subject to final approval by the Editor-in-Chief. Some papers may be published outside the special section, at the EIC discretion.

Timetable:	Deadline for manuscript submissions	December 31, 2017
	Expected publication date (tentative)	July 2018

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